

## Specifications

Insulation Resistance:	1,000M $\Omega$ min. at 500V DC
Dielectric Withstanding Voltage:	700V AC for 1 minute
Contact Resistance:	30m $\Omega$ max. at 10mA/20mV max.
Operating Temperature Range:	-55°C to +170°C
Mating Cycles:	10,000 insertions min.
Pin Count:	160 contact pins

## Materials and Finish

Housing: Polyetherimide (PEI), glass-filled  
 Contacts: Beryllium Copper (BeCu)  
 Plating: Gold over Nickel

## Features

- Card thickness 1.57mm

## Part Number (Details)

**IC-553 - 1 - MF**

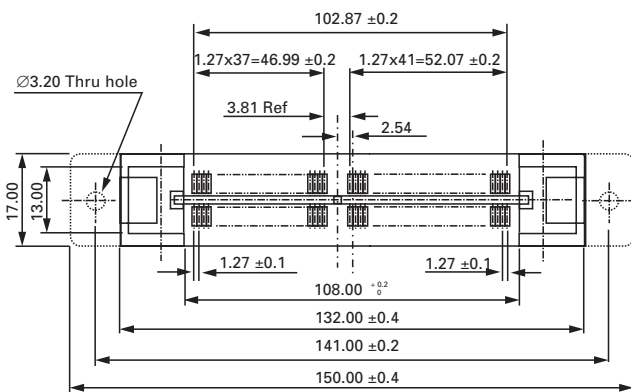
Series No.

Design No.

MF = Flanged  
 Unmarked = Not Flanged

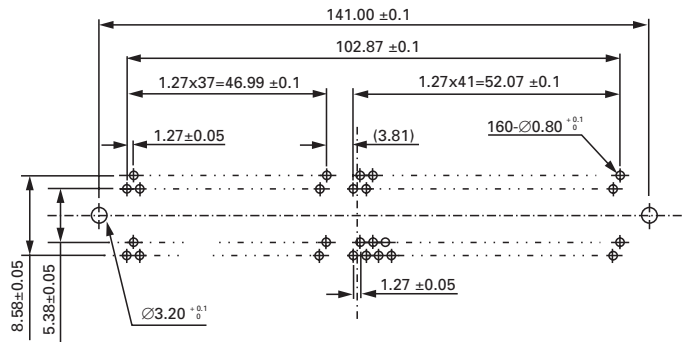


## Outline Socket Dimensions



## Recommended PC Board Layout

Top View from Socket



## Matching Module Dimensions

